PRODUCT ADVISORY

Data Sheet Specification Change for Intersil Product ISL59532IKEZ

Refer to:
PA11108

Date: October 26, 2011

October 26, 2011

To: Our Valued Intersil Customers

Subject: **Data Sheet Specification Change for Intersil Product ISL59532IKEZ**

This advisory is to inform you that Intersil has updated the data sheet specification for the listed ISL59532IKEZ product. The change to θ_{JA} for the HBGA (Heatsink Ball Grid Array) package in the Thermal Information section aligns the data sheet with the product characteristics. The updated data sheet is available on the Intersil web site at http://www.intersil.com/data/fn/fn7432.pdf.

Data sheet specification changes for θ_{JA} are as follows:

Thermal Resistance	Current Value	New Value	Units
356p HBGA	4.7 – 18*	24	°C/W

* Value based on the combination of airflow with or without heatsink.

There will be no change in external marking of the packaged parts. There have been no changes made to the die/silicon or device itself.

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to continue receiving product processed to the same established conditions and systems used for manufacturing of material supplied today.

If you have concerns with this advisory, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

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PA11108

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